

SOT2148-1

FBGA975, fine pitch ball grid array package, 975 terminals, 0.8 mm pitch, 27 mm x 27 mm x 1.63 mm body

16 February 2022

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	FBGA975
Package style descriptive code	FBGA (fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	22-12-2021
Manufacturer package code	98ASA01799D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	27	-	mm
package width	-	27	-	mm
seated height	-	1.63	1.82	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	975	-	



FBGA975, fine pitch ball grid array package, 975 terminals, 0.8 mm pitch, 27 mm x 27 mm x 1.63 mm body

2 Package outline

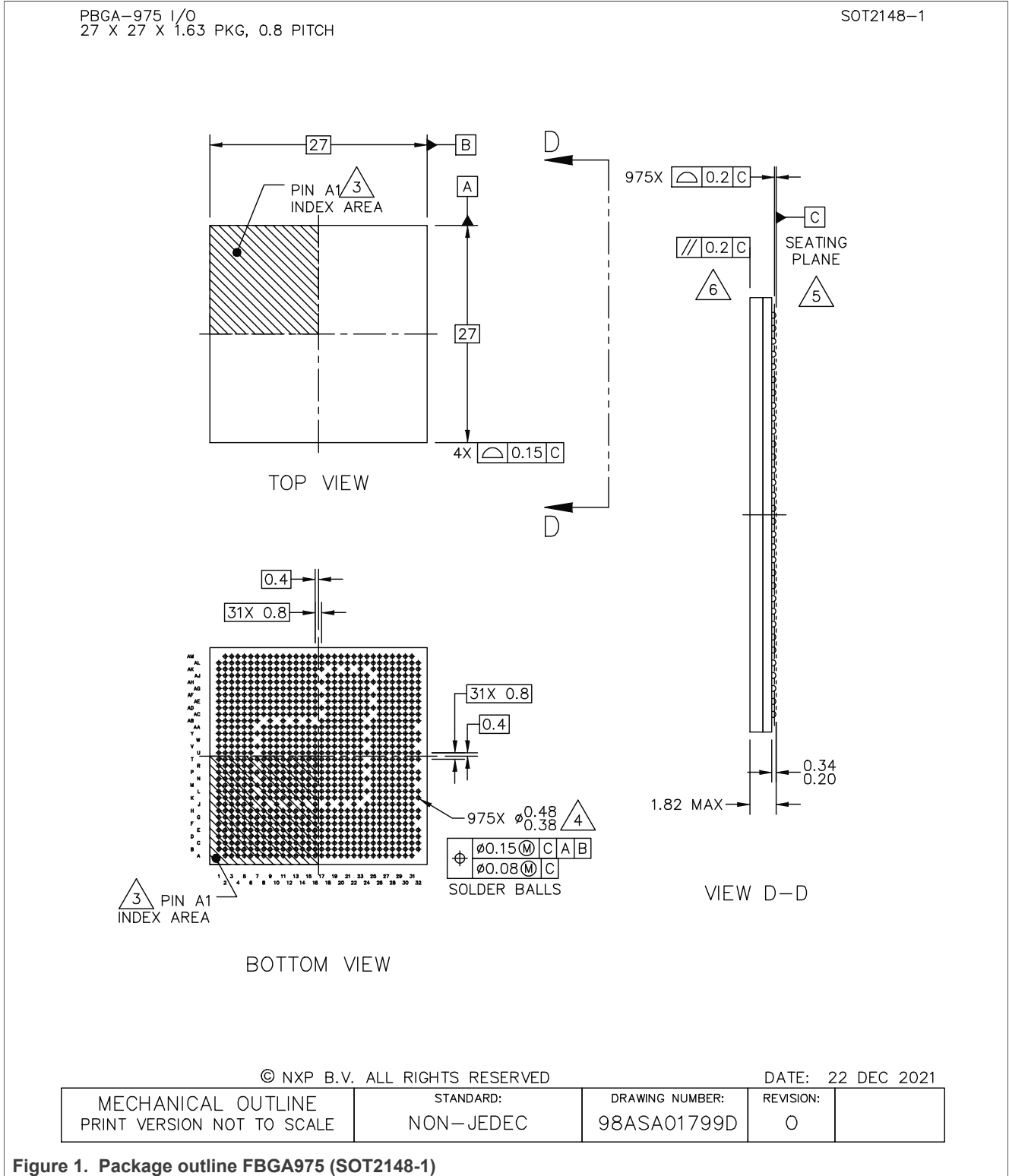
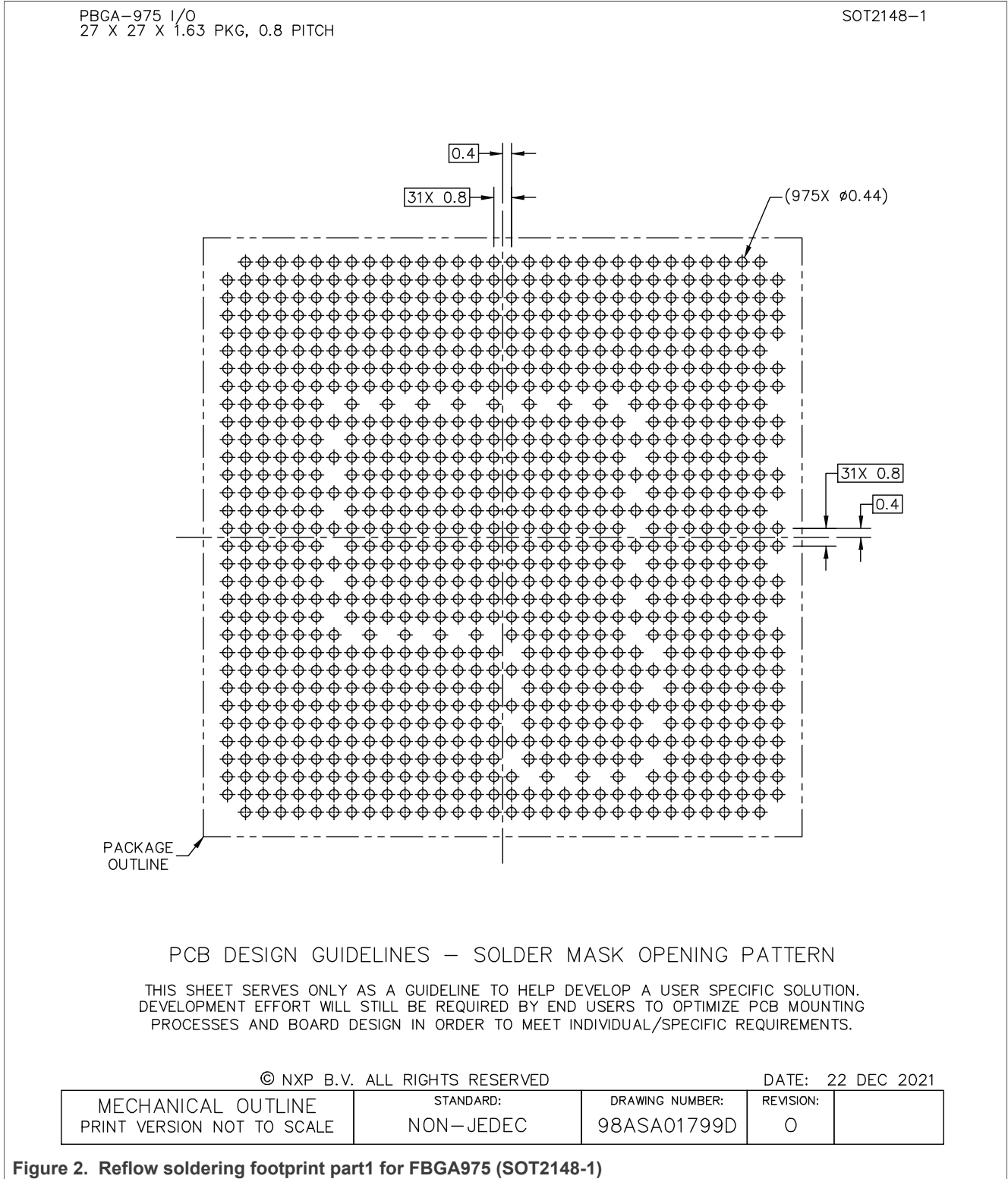
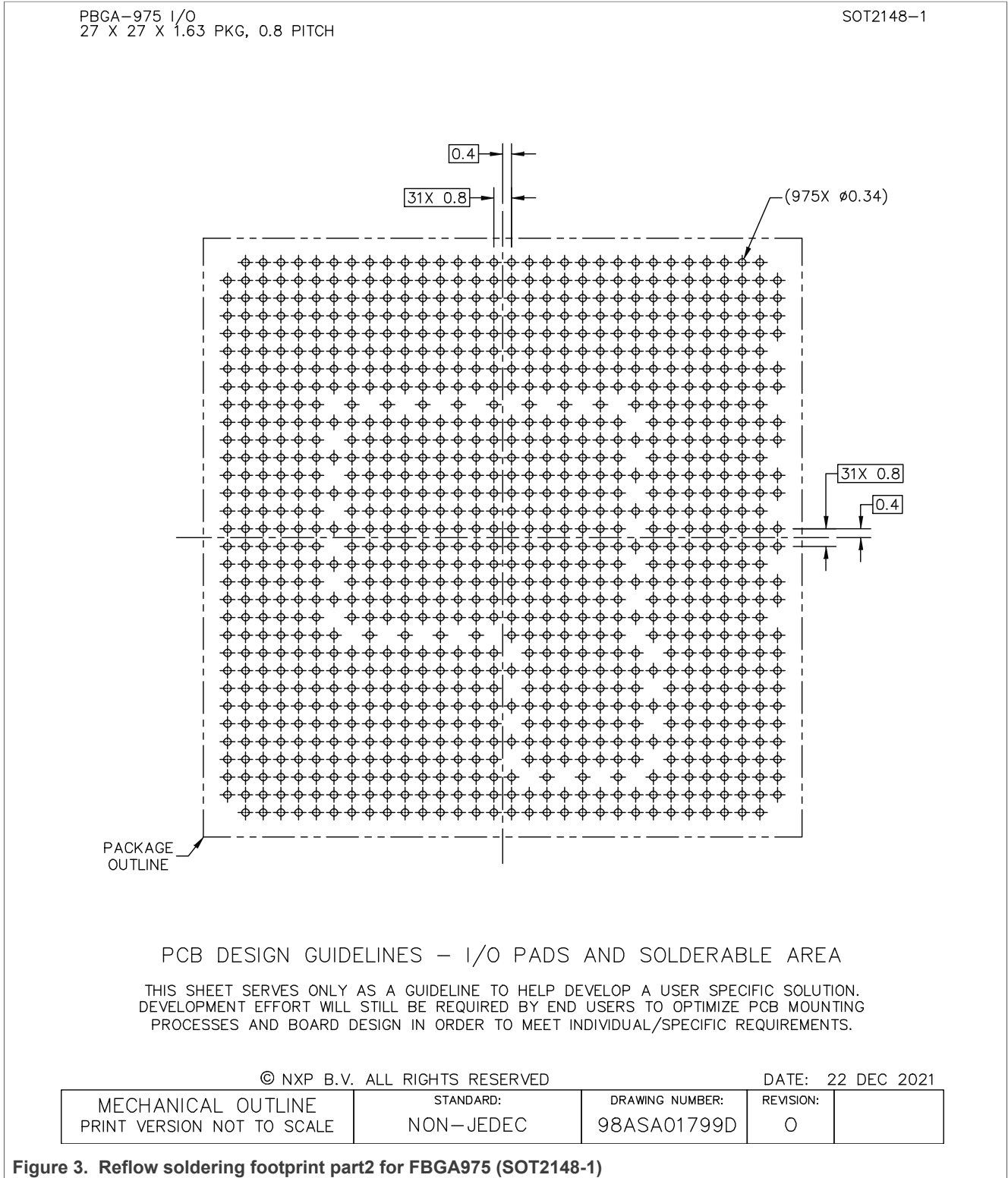


Figure 1. Package outline FBGA975 (SOT2148-1)

3 Soldering



FBGA975, fine pitch ball grid array package, 975 terminals, 0.8 mm pitch, 27 mm x 27 mm x 1.63 mm body



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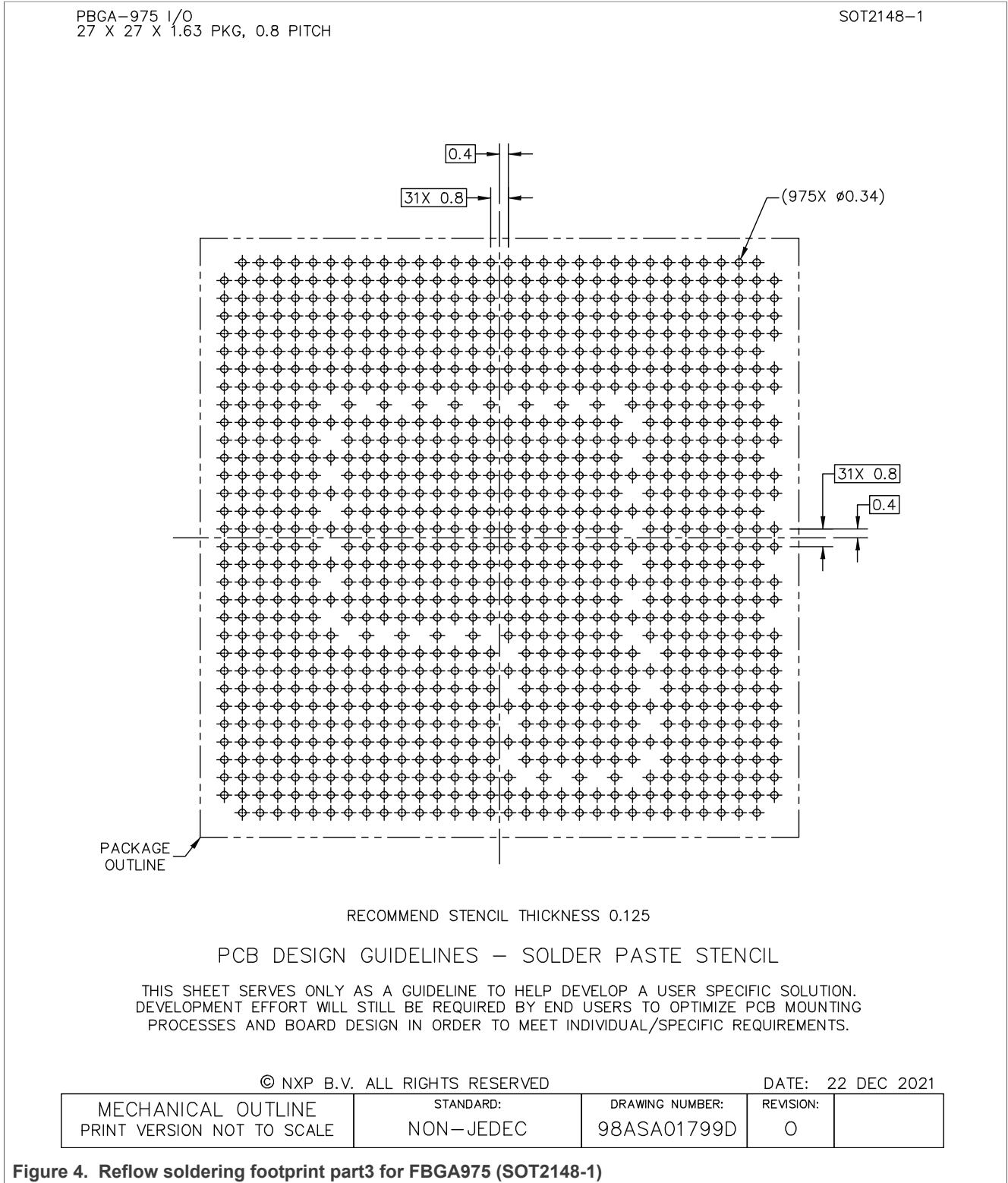


Figure 4. Reflow soldering footprint part3 for FBGA975 (SOT2148-1)

FBGA975, fine pitch ball grid array package, 975 terminals, 0.8 mm pitch, 27 mm x 27 mm x 1.63 mm body

PBGA-975 I/O
27 X 27 X 1.63 PKG, 0.8 PITCH

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NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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DATE: 22 DEC 2021

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01799D	REVISION: 0
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Figure 5. Package outline note FBGA975 (SOT2148-1)

4 Legal information

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